

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
8 January 2004 (08.01.2004)

PCT

(10) International Publication Number
WO 2004/003823 A1

(51) International Patent Classification⁷: **G06F 19/00**,
17/50, 17/10, 7/60

(21) International Application Number:

(22) International Filing Date: 27 June 2003 (27.06.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/187,323 1 July 2002 (01.07.2002) US

(71) Applicant: STRATASYS, INC. [US/US]; 14950 Martin
Drive, Eden Prairie, MN 55344-2020 (US).

(72) Inventor: PRIEDEMAN, William, R., Jr.; Stratasys,
Inc., 14950 Martin Drive, Eden Prairie, MN 55344-2020
(US).

(74) Agents: CHAPMAN, Gena, M. et al.; Kinney & Lange,
PA, Kinney & Lange Building, 312 South Third Street,
Minneapolis, MN 55415-1002 (US).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,
GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,
LK, LR, LS, LI, LU, LV, MA, MD, MG, MK, MN, MW,
MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD,
SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ,
VC, VN, YU, ZA, ZM, ZW.

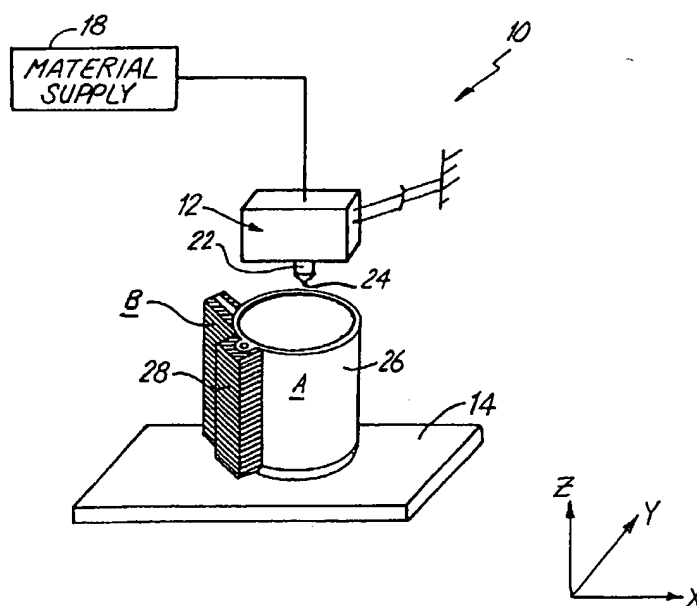
(84) Designated States (*regional*): ARIPO patent (GH, GM,
KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO,
SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM,
GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- before the expiration of the time limit for amending the
claims and to be republished in the event of receipt of
amendments

[Continued on next page]

(54) Title: MATERIAL AND METHOD FOR THREE-DIMENSIONAL MODELING



(57) Abstract: A three-dimensional model (26) and its support structure (28) are built by fused deposition modeling techniques, wherein a thermoplastic material containing silicone is used to form the support structure (28) and/or the model (26). The silicone acts as a release agent to facilitate removal of the support structure from the model after its completion. The thermoplastic material containing silicone exhibits good thermal stability, and resists build-up in the nozzle (24) of an extrusion head (12) or jetting head of a three-dimensional modeling apparatus (10).

WO 2004/003823 A1



For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

MATERIAL AND METHOD FOR THREE-DIMENSIONAL MODELING

BACKGROUND OF THE INVENTION

This invention relates to the fabrication of three-dimensional objects using additive process modeling techniques. More particularly, the invention relates to forming three-dimensional objects by depositing a first solidifiable material in a predetermined pattern so as to form a three-dimensional object, in coordination with the depositing of a second solidifiable material so as to provide a support structure for the three-dimensional object as it is being built.

Additive process modeling machines make three-dimensional models by building up a modeling medium, based upon design data provided from a computer aided design (CAD) system. Three-dimensional models are used for functions including aesthetic judgments, proofing the mathematical CAD model, forming hard tooling, studying interference and space allocation, and testing functionality. One technique is to deposit solidifiable modeling material in a predetermined pattern, according to design data provided from a CAD system, with the build-up of multiple layers forming the model.

Examples of apparatus and methods for making three-dimensional models by depositing layers of solidifiable modeling material from an extrusion head are described in Valavaara U.S. Patent No. 4,749,347; Crump U.S. Patent No. 5,121,329; Batchelder, et al. U.S. Patent No. 5,303,141; Crump U.S. Patent No. 5,340,433; Batchelder, et al. U.S. Patent No. 5,402,351; Crump, et al. U.S. Patent No. 5,503,785; Batchelder, et al. U.S. Patent No. 5,764,521; Danforth, et al. U.S. Patent No. 5,900,207; Batchelder, et al. U.S. Patent No. 5,968,561; Stuffie, et al. U.S. Patent No. 6,067,480; and Batchelder et al. U.S. Patent No. 6,238,613; all of which are assigned to Stratatsys, Inc., the assignee of the present invention. The modeling material may be supplied to the extrusion head in solid form, for example in the form of a flexible filament wound on a supply reel or in the form of a solid rod, as disclosed in U.S. Patent No. 5,121,329. As described in U.S. Patent No. 4,749,347, modeling material may alternatively

be pumped in liquid form from a reservoir. In any case, the extrusion head extrudes molten modeling material from a nozzle onto a base. The extruded material is deposited layer-by-layer in areas defined from the CAD model. A solidifiable material which adheres to the previous layer with an adequate
5 bond upon solidification is used as the modeling material. Thermoplastic materials have been found particularly suitable for these deposition modeling techniques.

Another layered-deposition technique for building models from a solidifiable material deposits droplets of modeling material from nozzles
10 of a jetting head. Examples of apparatus and methods for making three-dimensional models by depositing layers of solidifiable modeling material from a jetting head are described, for example, in U.S. Patent No. 5,136,515 to Helinski et al., and U.S. Patent No. 6,193,923 to Leyden et al.

In filament-fed Stratasys FDM® three-dimensional modeling
15 machines of the current art, a filament strand of the modeling material (or support material) is advanced by a pair of motor-driven feed rollers into a liquifier carried by the extrusion head. Inside the liquifier, the filament is heated to a flowable temperature. The liquifier is pressurized by the "pumping" of the strand of filament into the liquifier by the feed rollers. The
20 strand of filament itself acts as a piston, creating a pump. As the feed rollers continue to advance filament into the extrusion head, the force of the incoming filament strand extrudes the flowable material out from the dispensing nozzle where it is deposited onto a substrate removably mounted to a build platform. Stratasys FDM® three-dimensional modeling machines
25 of the current art use as the modeling material an acrylonitrile-butadiene-styrene (ABS) thermoplastic composition, a wax material, or a polycarbonate resin.

In creating three-dimensional objects by additive process techniques, such as by depositing layers of solidifiable material, it is the rule
30 rather than the exception that supporting layers or structures must be used underneath overhanging portions or in cavities of objects under construction, which are not directly supported by the modeling material itself. A support structure may be built utilizing the same deposition techniques and

apparatus by which the modeling material is deposited. The apparatus, under appropriate software control, produces additional geometry acting as a support structure for the overhanging or free-space segments of the object being formed. Support material is deposited either from a separate
5 dispensing head within the modeling apparatus, or by the same dispensing head that deposits modeling material.

In order to support the model, the support material must adhere to the modeling material. Also, as the support material typically is used to create base layers of deposited material upon which the model is
10 built, the support material should likewise removably adhere to the modeling substrate. Anchoring the model to support material creates the problem of removing the support structure from the finished model without causing damage to the model.

The problem of removing the support structure has been
15 addressed by forming a weak, breakable bond between the model and the support structure, such as is described in U.S. Patent No. 5,503,785. Support structures that must be broken apart from the object after it is built are known as "break-away" supports. High-impact polystyrene is commercially used to build break-away supports. Additionally, soluble
20 support materials are known, which wash away in a bath. Stratasys, Inc. offers a material disclosed in pending U.S. Patent Application Serial No. 10/019,160, sold under the name Waterworks™, for creating soluble supports.

Recently, high-temperature fused deposition modeling
25 machines have become known, which can build models from high-temperature, high-strength, engineering thermoplastics. Modeling with high-temperature engineering thermoplastics is highly desirable due to the durability of the materials, however, it creates difficulty in regards to the construction and removal of support structures. Candidate support
30 materials must withstand the high-temperature build environment in which the model is built without degrading or drooping. Such materials are generally strong and resistant to breakage. Yet, supports must be removed

from the model after its construction. Thus, there arises the problem of how to separate the supports from the completed model.

An apparatus and method for layered deposition of high-strength engineering polymers to manufacture durable three-dimensional objects is disclosed in U.S. Patent No. 6,067,480. The '480 patent discloses
5 high-pressure extrusion of polycarbonate, polyaryletherketone and poly(methylmethacrylate). The '480 patent makes no disclosure of support materials.

Apparatus and methods for building three-dimensional models
10 by layered deposition of high-temperature engineering thermoplastics are disclosed in pending U.S. Patent Applications, Serial No. 09/804,401, filed February 27, 2001 and Serial No. 10/018,673 filed December 13, 2001, each assigned to Stratasys, Inc. These applications specifically disclose the use of polycarbonates, polyetherimides, polyphenylsulfones, polysulfones,
15 polyethersulfones and amorphous polyamides for building a three-dimensional model, but disclose no materials formulated for use in building a break-away support structure for such a model.

High-temperature modeling and support materials for three-dimensional modeling are disclosed in pending U.S. Patent Application
20 Serial No. 09/854,220, filed May 11, 2001 and assigned to Stratasys, Inc. Removal of the support materials disclosed in the '220 application can be tedious.

There is a continuing need to improve techniques for easing removal of supports from models built from high-performance engineering
25 thermoplastics. It would be desirable to provide support materials for models made from such thermoplastics that will withstand a high temperature environment and can be more easily removed from the completed models.

BRIEF SUMMARY OF THE INVENTION

30 The present invention is a thermoplastic composition containing silicone, and a method for using the composition to build a three-dimensional model by layered deposition modeling. The thermoplastic composition contains up to about 10 weight percent silicone.

A method according to the present invention employs the thermoplastic composition containing silicone as a support material for building a support structure for the model while it is under construction, with the silicone acting as a release agent to facilitate removal of the support structure from the model after its completion. The silicone release agent also exhibits good thermal stability, facilitating use of the material in high-temperature build environments. Advantageously, the silicone further serves to prevent a build-up of material in the nozzle of an extrusion head or jetting head of a three-dimensional modeling apparatus. Thus, the thermoplastic composition of the present invention is used to advantage as a modeling material for building the model itself, in addition to its use as a support material.

For use as a support material, the thermoplastic composition of the present invention preferably contains between about 1 and 10 weight percent silicone. For use as a modeling material, the thermoplastic composition of the present invention contains a lesser amount of silicone, preferably between about 0.5 and 2 weight percent silicone. A base polymer of the thermoplastic composition is selected based upon various physical, thermal and rheological properties demanded by the deposition modeling process.

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 is a diagrammatic illustration of a model and a support structure therefor formed using layered extrusion techniques.

DETAILED DESCRIPTION

The present invention is described with reference to a deposition modeling system of the type shown in Figure 1. Figure 1 shows an extrusion apparatus 10 building a model 26 supported by a support structure 28 according to the present invention. The extrusion apparatus 10 includes an extrusion head 12, a material-receiving base 14 and a material supply 18. The extrusion head 12 moves in X and Y directions with respect to the base 14, which moves in a vertical Z direction. The material supply 18 supplies a feedstock of material to the extrusion head 12. In the described embodiment, a solid feedstock of material is supplied to the

extrusion head 12, and is melted in a liquifier 22 carried by the extrusion head 12. The liquifier 22 heats the feedstock material to a temperature slightly above its solidification point, reducing it to a molten state. Molten material is extruded through a nozzle 24 of the liquifier 22 onto the base 14.

5 The feedstock may take the form of a continuous filament, rods, slugs, pellets, granulations or the like.

The movement of the extrusion head is controlled so as to deposit material onto the base 14 in multiple passes and layers to build the three-dimensional model 26 and further to build the support structure 28
10 defined so as to physically support the model 26 as it is being built. The model 26 and its support structure 28 are build up on the base 14 within a build chamber (not shown) having an environment controlled so as to promote thermal solidification. A first layer of the deposited material adheres to the base 14 so as to form a foundation, while subsequent layers
15 of material adhere to one another.

A modeling material A is dispensed to form the model 26, and a support material B is dispensed in coordination with the dispensing of modeling material A to form the support structure 28. For convenience, the extrusion apparatus 10 is shown with only one material supply 18. It should
20 be understood, however, that in the practice of the present invention, the modeling material A and the support material B are provided to the extrusion apparatus 10 as separate feedstocks of material from separate material supplies.

In the described embodiment, the modeling material A and the
25 support material B are deposited as substantially continuous "roads" in horizontal layers from an extrusion head, and are supplied to the extrusion head in solid form. It will be understood by those skilled in the art that the invention can be practiced with advantage in various other types of modeling machines as well, including those that employ a jetting head, and that the
30 materials may alternatively be supplied to the extrusion head in liquid form.

Rheology of Modeling and Support Materials:

The modeling material A and support material B must satisfy a large number of modeling criteria for the particular modeling system in which they are used, relating generally to thermal properties, strength, viscosity and adhesion. The modeling material A and support material B must have a melt viscosity suitable for the modeling process. Ideally, materials used for fused deposition modeling have low melt viscosity. The melt viscosity must be low enough at the extrusion temperature so that it can be extruded as a generally continuous road or bead. Also, the melt viscosity at the extrusion temperature must be low enough so that deposited roads or beads of material have little melt strength, allowing them to lay flat rather than curl up. Melt viscosity is lowered by increasing the temperature at which the material is extruded. But, a higher extrusion temperature increases energy consumption, increases heat generation and increases the opportunity for the material to degrade.

In theory, the viscosity of a melt is related to the molecular weight of the material, and as it approaches the critical molecular weight, properties diminish. So, the lower limit on melt viscosity is defined as that at the critical molecular weight, but virtually all commercial grade polymers exceed the critical molecular weight to deliver good physical properties.

Melt viscosity may be measured by its inverse parameter, melt flow. A material used to build models in a Stratasys FDM® modeling machine which has a filament-pump extruder must have a high melt flow at the extrusion temperature, so as to be extruded as a continuous bead under a relatively low pressure of about 211 kg/cm (3000 psi) or less. A desirable high melt flow for material deposited by a filament-pump type extruder is greater than about 5 gms/10 minutes, as measured by ASTM D1238, under a load of 1.2 kg at the extrusion temperature. Most preferably, the melt flow is between 5-30 g/10 minutes. A lower melt flow (higher viscosity) is suitable for high pressure extrusion, such as by the apparatus disclosed in U.S. Patent No. 6,067,480.

To properly support the model under construction, the support material B must bond to itself (self-laminate). The support materials B must

form a weak, breakable bond to modeling material A (co-laminate), so that it can be separated from the completed model without causing damage to the model. Where the support structure is built up from the base, support material B must additionally bond to the base.

5 To produce a dimensionally accurate model, the modeling and support materials must exhibit little shrinkage upon cooling in the conditions of the build envelope. Any shrinkage of the support material B must match that of the modeling material A. A shrink differential in the materials would cause stresses and bond failures along the model/support structure joint.

10 Amorphous polymers typically have a shrinkage upon solidification of less than or equal to 0.010 inch/inch according to ASTM injection-molding test standards. The shrinkage characteristic of amorphous polymers is acceptable for deposition modeling purposes, while crystalline polymers exhibit shrinkage too high for deposition modeling. Fillers may be added to

15 the materials to reduce shrinkage. Crystalline additives may be added to the materials of the present invention, so long as they are added in an amount small enough so that the materials continue to exhibit the shrinkage characteristic of an amorphous polymer.

 Selection of a particular modeling material A can be made

20 according to the particular application of the finished model. The support material B must have sufficient mechanical strength in solid form to provide support to a model during its formation. The support material B must resist forces by the modeling material A, or the model will exhibit undesirable curling and deformation. A tensile strength of between 211 kg/cm (3000

25 psi) and 844 kg/cm (12,000 psi) is typically desired.

 The modeling material A and support material B, when supplied in filament or rod form, must be strong enough to be shipped without breaking. When supplied in filament form, the materials must further have the strength and flexibility to be formed into a filament, be spooled and

30 unspooled, and be fed through the extrusion apparatus without breakage. Similarly, materials supplied in filament form must have sufficient rigidity to not be deformed by compressive forces during feeding through the extrusion apparatus.

As to thermal properties, the modeling material A and support material B should have similar heat deflection properties, so that both materials can successfully be extruded into the same build chamber. As taught in U.S. Patent No. 5,866,058, building the model in a chamber heated to a temperature higher than the solidification temperature of the thermoplastic or other thermally solidifiable modeling material, followed by gradual cooling, relieves stresses from the material. The stresses are annealed out of the model while it is being built so that the finished model is stress free and has very little distortion. As is further taught in the '058 patent, a modeling material should have a glass transition temperature (T_g) higher than the temperature of the build chamber, so that the model does not become so weak that it droops. The preferred temperature of the build chamber is thus in a range between the solidification temperature of modeling material A and its creep relaxation temperature (creep relaxation temperature is defined as the point at which the stress relaxation modulus has dropped by a factor of ten from its low temperature limit). Likewise, the glass transition temperature of the support material B should be higher than the temperature of the build chamber, so that the support structure will not deform and will maintain structural fidelity of the model that it supports. It has been discovered through experimentation that the glass transition temperature (or heat deflection temperature) of the support material B should be within about 20 °C of the of the modeling material A, preferably with 15 °C. The addition of fillers to the materials can have the effect of raising a material's glass transition temperature. In practice, glass transition temperature is indicated by the heat deflection temperature. Heat deflection temperature of the exemplary materials disclosed herein is measured by the DMA softening point of the material.

Exemplary polymers for use as modeling material A or support material B, or for use in formulating such materials, include polyethersulfones, polyetherimides, polyphenylsulfones, polyphenylenes, polycarbonates, high-impact polystyrenes, polysulfones, polystyrenes, acrylics, amorphous polyamides, polyesters, nylons, PEEK, PEAK and ABS. The selection of a particular material formulation is made based upon the

various physical, thermal and rheological properties demanded by the deposition modeling process, such as have been described. A support material is further chosen based upon the strength of the bond it will have with the modeling material.

5 Testing of Materials:

 The following are examples of material formulations which were tested for use as support materials in a very high-temperature modeling environment (i.e. build chamber temperature of 200 °C or greater). The material formulations were tested as support materials for a polyphenylsulfone modeling material. Specifically, in each case, the polyphenylsulfone modeling material is Radel® R 5600 NT (available from BP Amoco). This polyphenylsulfone resin has a heat deflection temperature of 236 °C, and a melt flow in the range of 20-30 gms/10 min. at 400 °C under a 1.2 kg load. Example 3 embodies the present invention, while Example 1 and 2 are comparative examples.

 All of the materials tested met the rheology criteria discussed above. In each case, techniques conventional in polymer chemistry were used to compound the component materials. The exemplary materials were successfully formed into modeling filament of a very small diameter (on the order of 1.778 mm (0.070 inches)), were dried to less than 700 ppm moisture content, and were used in a filament-fed deposition modeling machine. Materials according to the examples given were tested using filament-fed layered deposition modeling machines of the type disclosed in pending U.S. Applications, Serial Nos. 09/804,401 (filed February 27, 2001) and 10/018,673 (filed December 13, 2001).

Example 1

 Models of various sizes were built in a build chamber having a temperature of about 200-225°C, using the polyphenylsulfone modeling material and a support material comprising a blend of polyphenylsulfone and amorphous polyamide. In some cases, the support material further included polysulfone. Weight percent ranges of the various component materials were between about 60 and 90

weight percent polyphenylsulfone, and between about 10 and 40 weight percent amorphous polyamide blend, or between about 60 and 90 weight percent polyphenylsulfone, between about 1 and 40 weight percent polysulfone and between about 10 and 40 weight percent amorphous polyamide blend. A particular exemplary resin tested is a blend of 50 weight percent Radel® R 5600 NT polyphenylsulfone (available from BP Amoco), 25 weight percent Udel® P 1710 NT 15 polysulfone (available from BP Amoco), and 25 weight percent EMS TR 70 amorphous polyamide (available from EMS-Chemie AG of Switzerland). This resin has a heat deflection temperature of 224 °C and a melt flow similar to that of the modeling material. The support material was extruded from a liquifier having a temperature of about 350°C to form a support structure for a model built using the polyphenylsulfone resin.

The support material according to this example was satisfactory for models that took less than about 20 hours to build, but failed for models that had a longer build time. It was observed that the support material exhibited thermally instability after about 20 hours in the build chamber. The thermally instability manifested by the material becoming dark and eventually blackening, and becoming strongly adhered to the model. Desirably, a material will survive build times of up to about 200 hours, to permit the building of large and complex parts. Thus, while the support material of the present example was found satisfactory for supporting small parts, it is not suitable for more general high-temperature use.

Example 2

Test models were built in a build chamber having a temperature of about 200- 225°C, using the polyphenylsulfone modeling material and a support material which comprised various resins of polyethersulfone, polyphenylsulfone or polyetherimide (i.e., Ultem™). These materials exhibited favorable thermal stability, but could not be broken away from the model. The support material containing polyphenylsulfone adhered very strongly to the model. The

support material containing polyetherimide adhered fairly strongly to the model, and the support material containing polyethersulfone, while exhibiting the least adherence to the model, adhered too strongly for suitable use.

5

Example 3

Large and small polyphenylsulfone models were built in a build chamber having a temperature of about 200- 225°C, using a support material comprising a polyethersulfone base polymer and a silicone release agent. For convenience, commercially available compounds were used to provide a "masterbatch" containing silicone, which was compounded with the base polymer. Various masterbatches were tested, which included polypropylene, linear low-density polyethylene, and high-impact polystyrene. Additionally, various silicones were tested, ranging in viscosity from about 60,000 centistokes (intermediate viscosity) to 50 million centistokes (very high viscosity). The very high viscosity silicones have a high molecular weight, while the lower viscosity silicones have a lower molecular weight.

It was found that intermediate viscosity silicone was a much better release agent than the very high viscosity silicone, and that the high-impact polystyrene masterbatch released more easily from the polyphenylsulfone modeling material than did the other masterbatches tested. In a preferred embodiment, the masterbatch contained about 75 weight percent of a high-impact polystyrene co-polymer and about 25 weight percent of a 60,000 centistoke (cSt) viscosity silicone. In this embodiment, the support material comprised between about 90- 95 weight percent polyethersulfone, between about 3-8 weight percent high-impact polystyrene, and between about 1-3 weight percent silicone. This composition was demonstrated using BASF, Ultrason E-1010 polyethersulfone and Dow-Corning MB25-504 styrene butadiene copolymer containing hydroxy-terminated poly dimethyl siloxane (i.e. hydroxy-terminated silicone). This material was extruded from a liquifier having a temperature of about 420°C to successfully form a support structure for a model built using the polyphenylsulfone resin. The

support structure satisfactorily released from the model after its construction.

The support material of the present example exhibited a tensile strength of between 352 kg/cm (5000 psi) and 844 kg/cm (12,000 psi), exhibited a shrinkage typical of amorphous polymers, a melt flow in the range of about 5-30 gms/10 min. under a 1.2 kg load at a temperature of up to 450 °C, and a heat deflection temperature of about 232 °C.

Discussion of Results

It was demonstrated that adding a small amount of silicone to a base polymer weakened the bond between the base polymer and the modeling material, enabling use of the polymer to form a support structure that could be broken-away from the model. An intermediate viscosity silicone (on the order of about 10^4 - 10^5 centistokes) provided good release characteristics, although it is expected that a variety of silicones can be used to advantage in the present invention.

As the silicone release agent exhibited thermal resistance at temperatures of 225 °C for over 200 hours, the present invention is particularly useful in supporting models made from high-temperature thermoplastics in a very hot environment.

While the composition of the present invention was demonstrated using a polyethersulfone base polymer, the silicone release agent can be added to a variety of other base polymers to likewise lessen adhesion of the support structure to the model. A base polymer is selected based upon various physical, thermal and rheological properties demanded by the deposition modeling process. For high-temperature processes, silicone added to a polyphenylsulfone or polyetherimide base polymer will exhibit good thermal stability. Other potential base polymers for use in various build environments include polyphenylenes, polycarbonates, high-impact polystyrenes, polysulfones, polystyrenes, acrylics, amorphous polyamides, polyesters, nylons, PEEK, PEAK and ABS. Where adhesion between a base

polymer and a modeling material is higher, a greater amount of silicone can be added. A suitable amount of silicone will weaken but not destroy the bond between the support structure and the model, providing adhesion sufficient to support the model under construction. It is
5 expected that up to about 10 weight percent silicone may be desired in some cases.

While a high-impact polystyrene co-polymer was used in demonstrating the present invention, such co-polymer is but one example of a co-polymer which may be included in the composition of
10 the present invention. The high-impact polystyrene masterbatch was used as a matter of convenience in compounding the silicone with the base polymer. Those skilled in the art will recognize that various masterbatches may be used (e.g., one made with the base polymer of the support material), that other techniques for compounding may be
15 used which do not require a masterbatch (e.g., liquid silicone could be added directly to the base polymer), and that various other co-polymers may be included in the thermoplastic composition, in various amounts, to satisfy processing demands of a given application.

An unexpected benefit of the thermoplastic material
20 containing silicone is that this material resisted build-up in the nozzle of the extrusion head liquifier. This attribute of the material, though unintended, is highly desirable. Typically, the liquifier of an extrusion-based layered deposition modeling machine needs to be replaced after extrusion of only about 32 kg (7 pounds) of material, due to an
25 unacceptable build up of material in the nozzle. Resistance to clogging of the material containing silicone was observed to surpass that of any materials heretofore known in the art. The nozzles of liquifiers used to extrude the thermoplastic material containing silicone extruded over 18 kg (40 pounds) of the material before needing replacement. Nozzle life
30 was thus extended by over 400 percent. Hence, silicone was demonstrated to provide the thermoplastic with characteristics desirable for modeling materials as well as support materials.

Resistance to nozzle clogging was demonstrated with compositions that included as little as 0.75 weight percent silicone. For modeling materials, the amount of silicone in the material may thus be kept very small, between about 0.5 weight percent and 2 weight percent, to prolong the liquifier life without degrading the strength of the modeling material. As will be recognized by those skilled in the art, the higher viscosity silicone, which has a lesser release ability, may be beneficial as an additive to the modeling material. As will be further recognized by those skilled in the art, where silicone is contained in both the modeling and support material, a reduced amount of silicone in the support material may be preferred.

Also as will be recognized by those skilled in the art, the modeling material A and support material B may include inert and/or active filler materials. The fillers can provide enhanced material properties which may be desirable depending upon the intended use of the resulting model. For instance, fillers can provide RF shielding, conductivity, or radio opaque properties (useful for some medical applications). Fillers can alternatively degrade material properties, but this may be acceptable for some uses. For instance, an inexpensive filler can be added to the modeling material A or support material B to decrease the cost of these materials. Fillers can also change thermal characteristics of the materials, for instance a filler can increase the heat resistance of a material, and a filler can reduce material shrinkage upon thermal solidification. Exemplary fillers include glass fibers, carbon fibers, carbon black, glass microspheres, calcium carbonate, mica, talc, silica, alumina, silicon carbide, wollastonite, graphite, metals and salts.

Filler materials which will assist in removal of the support structure can also be used in the composition of the present invention. For instance, a filler material that swells when contacted by water or another solvent will tend to be useful in breaking down the support structure. A filler material that evolves gas when contacted by water or

another solvent will likewise tend to be useful in breaking down the support structure.

Those skilled in the art will recognize that innumerable other additives may also be to modify material properties as desired for particular applications. For instance, the addition of a plasticizer will lower the heat resistance and melt flow of a thermoplastic material. The addition of dyes or pigments can be done to change color. An antioxidant can be added to slow down heat degradation of material in the extruder.

The modeling and support materials A and B of this foregoing examples may be molded into filament, rods, pellets or other shapes for use as a modeling feedstock, or it may be used as a liquid feedstock without prior solidification. Alternatively, the mixture may be solidified and then granulated.

It should be noted that while materials are referred to herein as either "modeling" or "support" materials, these materials may be interchanged so as to form a model using the so-called "support" material and to form a support structure for that model using the so-called "modeling" material. In a given build process, however, the material used for forming the model will desirably have properties that are superior to those of the material used to form its support structure (e.g., greater strength and toughness).

Although the present invention has been described with reference to exemplary embodiments, it should be understood that the invention is not limited to the details of the embodiments but is defined by the scope of the following claims.

CLAIM(S):

1. An additive-process method for building a three-dimensional model comprising the step of:
depositing layers of a thermoplastic composition
5 containing between about 0.5 and 10 weight percent silicone.
2. The method of claim 1, wherein the thermoplastic composition contains less than about 2 weight percent silicone and the thermoplastic composition forms the model.
- 10 3. The method of claim 1, wherein the thermoplastic composition contains greater than about 1 weight percent silicone and the thermoplastic composition forms a support structure for the model.
4. The method of claim 1, wherein the thermoplastic composition further comprises a base polymer selected from the group
15 consisting of polyethersulfones, polyetherimides, polyphenylsulfones, polyphenylenes, polycarbonates, high-impact polystyrenes, polysulfones, polystyrenes, acrylics, amorphous polyamides, polyesters, nylons, PEEK, PEAK and ABS.
5. The method of claim 1, wherein the thermoplastic
20 composition has a heat deflection temperature of greater than about 220 °C.
6. The method of claim 5, wherein the thermoplastic composition has a melt flow in the range of about 5-30 gms/10 min. under a 1.2 kg load at a temperature of up to 450 °C, and a tensile
25 strength of between about 352 kg/cm (5,000 psi) and 844 kg/cm (12,000 psi).
7. The method of claim 6, wherein the thermoplastic composition further comprises a base polymer selected from the group consisting of polyethersulfones, polyphenylsulfones and
30 polyetherimides.
8. The method of claim 1, wherein the silicone has a viscosity on the order of about 10^4 - 10^5 centistokes.

9. The method of claim 1, wherein the silicone is hydroxy-terminated polysiloxane.

10. The method of claim 1, wherein the thermoplastic composition has a heat deflection temperature of greater than about
5 40 °C, a melt flow in the range of about 5-30 gms/10 min. under a 1.2 kg load at a temperature of up to 450 °C, and a tensile strength of between about 211 kg/cm (3,000 psi) and 844 kg/cm (12,000 psi).

11. The method of claim 1, wherein the thermoplastic composition is deposited into a build chamber having a temperature of
10 between about 180 °C and 250 °C.

12. An additive-process method for building a three-dimensional model and a support structure therefor, the model being formed by layered deposition of a solidifiable modeling material and the support structure being formed by layered deposition of a solidifiable
15 support material, wherein the support material is a thermoplastic composition comprising between about 1-10 weight percent of a silicone release agent.

13. The method of claim 12, wherein the support material further comprises a base polymer selected from the group consisting of
20 polyethersulfones, polyetherimides, polyphenylsulfones, polyphenylenes, polycarbonates, high-impact polystyrenes, polysulfones, polystyrenes, acrylics, amorphous polyamides, polyesters, nylons, PEEK, PEAK and ABS.

14. The method of claim 13, wherein the base polymer is
25 polyethersulfone and wherein the support material further comprises high-impact polystyrene.

15. The method of claim 14, wherein the modeling material comprises as a major component a polyphenylsulfone resin.

16. The method of claim 12, wherein the support material
30 further comprises a polyethersulfone base polymer.

17. The method of claim 16, wherein the support material further comprises high-impact polystyrene, and wherein the modeling material comprises as a major component a polyphenylsulfone resin.

18. A thermoplastic composition for use in layered-deposition three-dimensional modeling, comprising a base polymer selected from the group consisting of polyethersulfones, polyetherimides, polyphenylsulfones, polyphenylenes, polycarbonates, high-impact polystyrenes, polysulfones, polystyrenes, acrylics, amorphous polyamides, polyesters, nylons, PEEK, PEAK and ABS, and between about 0.5-10 weight percent silicone, and having a heat deflection temperature of greater than about 40 °C, a melt flow in the range of about 5-30 gms/10 min. under a 1.2 kg load at a temperature of up to 450 °C, and a tensile strength of between about 211 kg/cm (3,000 psi) and 844 kg/cm (12,000 psi).

19. The thermoplastic composition of claim 18, wherein the base polymer is selected from the group consisting of polyethersulfones, polyphenylsulfones and polyetherimides, and wherein the heat deflection temperature is greater than about 220 °C.

20. The thermoplastic composition of claim 19, wherein the composition exhibits thermally stability for a time period of at least 200 hours at temperatures of up to about 225 °C.

21. The thermoplastic composition of claim 18, wherein the silicone is hydroxy-terminated polysiloxane.

22. The thermoplastic composition of claim 18, wherein the weight percent of the base polymer in the composition ranges from about 60 percent to about 99 percent.

23. The thermoplastic composition of claim 22, wherein the thermoplastic composition further comprises between about 3 - 15 weight percent high-impact polystyrene.

24. The thermoplastic composition of claim 23, wherein the base polymer is polyethersulfone.

25. The thermoplastic composition of claim 24, wherein the weight percent of polyethersulfone in the composition ranges from about 90-95 percent, the weight percent of high-impact polystyrene in the composition ranges from about 3-8, and the weight percent of the

silicone release agent in the composition ranges from about 1-3 percent.

26. The thermoplastic composition of claim 18, in the form of a filament.

1 / 1

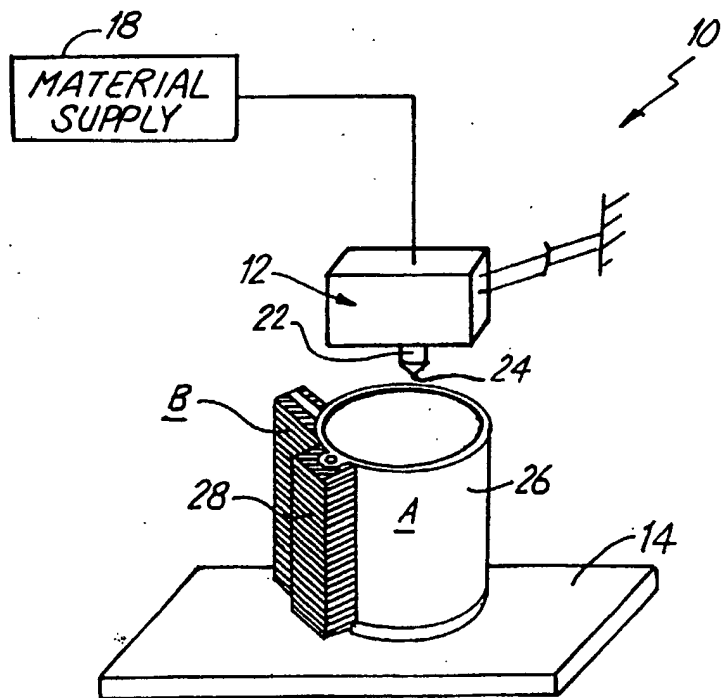
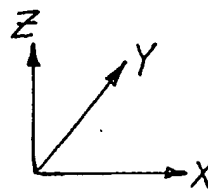


FIG. 1



INTERNATIONAL SEARCH REPORT

International application No.
PCT/US03/20088**A. CLASSIFICATION OF SUBJECT MATTER**

IPC(7) : G06F 19/00, 17/50, 17/10, 7/60

US CL : 700/118, 119; 703/1, 2

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

U.S. : 700/118, 119; 703/1, 2, 3

Documentation searched other than minimum documentation searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

EAST

Search terms: thermoplastic, silicone, models, weight, additive process, tensile, heat deflection temperature

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	US 6,067,480 A (STUFFLE et al) 23 May 2000, Abstract, Background and Summary of the Invention.	1-26
Y	US 6,214,279 B1 (YANG et al) 10 April 2001, Abstract, FIG. 7, Background and Summary of the Invention.	1-26
Y, P	US 6,572,228 B2 (KAGA et al) 3 June 2003, Summary of the Invention.	1-26

☐ Further documents are listed in the continuation of Box C.
 ☐ See patent family annex.

* Special categories of cited documents:	"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
"A" document defining the general state of the art which is not considered to be of particular relevance	"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
"E" earlier document published on or after the international filing date	"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art
"I" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)	"&" document member of the same patent family
"O" document referring to an oral disclosure, use, exhibition or other means	
"P" document published prior to the international filing date but later than the priority date claimed	

Date of the actual completion of the international search

27 OCTOBER 2003

Date of mailing of the international search report

19 NOV 2003

Name and mailing address of the ISA/US
Commissioner of Patents and Trademarks
Box PCT
Washington, D.C. 20231

Facsimile No. (703) 305-3230

Authorized officer

Kevin Teska

Telephone No. (703) 305-3900

Peggy Harrod